

SN74CBT16811C  
24-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS  
5-V BUS SWITCH WITH -2-V UNDERSHOOT PROTECTION

SCDS118C – JANUARY 2003 – REVISED OCTOBER 2003

- Member of the Texas Instruments Widebus™ Family
- Undershoot Protection for Off-Isolation on A and B Ports Up To -2 V
- B-Port Outputs Are Precharged by Bias Voltage (BIASV) to Minimize Signal Distortion During Live Insertion and Hot-Plugging
- Supports PCI Hot Plug
- Bidirectional Data Flow, With Near-Zero Propagation Delay
- Low ON-State Resistance ( $r_{on}$ ) Characteristics ( $r_{on} = 3 \Omega$  Typical)
- Low Input/Output Capacitance Minimizes Loading and Signal Distortion ( $C_{io(OFF)} = 5.5 \text{ pF}$  Typical)
- Data and Control Inputs Provide Undershoot Clamp Diodes
- Low Power Consumption ( $I_{CC} = 3 \mu\text{A}$  Max)
- $V_{CC}$  Operating Range From 4 V to 5.5 V
- Data I/Os Support 0 to 5-V Signaling Levels (0.8-V, 1.2-V, 1.5-V, 1.8-V, 2.5-V, 3.3-V, 5-V)
- Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)
- Supports Both Digital and Analog Applications: PCI Interface, Memory Interleaving, Bus Isolation, Low-Distortion Signal Gating

DGG, DGV, OR DL PACKAGE  
(TOP VIEW)

BIASV	1	56	1OE
1A1	2	55	2OE
1A2	3	54	1B1
1A3	4	53	1B2
1A4	5	52	1B3
1A5	6	51	1B4
1A6	7	50	1B5
GND	8	49	GND
1A7	9	48	1B6
1A8	10	47	1B7
1A9	11	46	1B8
1A10	12	45	1B9
1A11	13	44	1B10
1A12	14	43	1B11
2A1	15	42	1B12
2A2	16	41	2B1
$V_{CC}$	17	40	2B2
2A3	18	39	2B3
GND	19	38	GND
2A4	20	37	2B4
2A5	21	36	2B5
2A6	22	35	2B6
2A7	23	34	2B7
2A8	24	33	2B8
2A9	25	32	2B9
2A10	26	31	2B10
2A11	27	30	2B11
2A12	28	29	2B12

#### description/ordering information

The SN74CBT16811C is a high-speed TTL-compatible FET bus switch with low ON-state resistance ( $r_{on}$ ), allowing for minimal propagation delay. Active Undershoot-Protection Circuitry on the A and B ports of the SN74CBT16811C provides protection for undershoot up to -2 V by sensing an undershoot event and ensuring that the switch remains in the proper OFF state. The device also precharges the B port to a user-selectable bias voltage (BIASV) to minimize live-insertion noise.



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 **TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

# SN74CBT16811C

## 24-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS

### 5-V BUS SWITCH WITH -2-V UNDERSHOOT PROTECTION

SCDS118C – JANUARY 2003 – REVISED OCTOBER 2003

#### description/ordering information (continued)

The SN74CBT16811C is organized as two 12-bit bus switches with separate output-enable ( $1\overline{OE}$ ,  $2\overline{OE}$ ) inputs. It can be used as two 12-bit bus switches or as one 24-bit bus switch. When  $\overline{OE}$  is low, the associated 12-bit bus switch is ON, and the A port is connected to the B port, allowing bidirectional data flow between ports. When  $\overline{OE}$  is high, the associated 12-bit bus switch is OFF, and a high-impedance state exists between the A and B ports. The B port is precharged to BIASV through the equivalent of a 10-k $\Omega$  resistor when  $\overline{OE}$  is high, or if the device is powered down ( $V_{CC} = 0$  V).

During insertion (or removal) of a card into (or from) an active bus, the card's output voltage may be close to GND. When the connector pins make contact, the card's parasitic capacitance tries to force the bus signal to GND, creating a possible glitch on the active bus. This glitching effect can be reduced by using a bus switch with precharged bias voltage (BIASV) of the bus switch equal to the input threshold voltage level of the receivers on the active bus. This method will ensure that any glitch produced by insertion (or removal) of the card will not cross the input threshold region of the receivers on the active bus, minimizing the effects of live-insertion noise.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### ORDERING INFORMATION

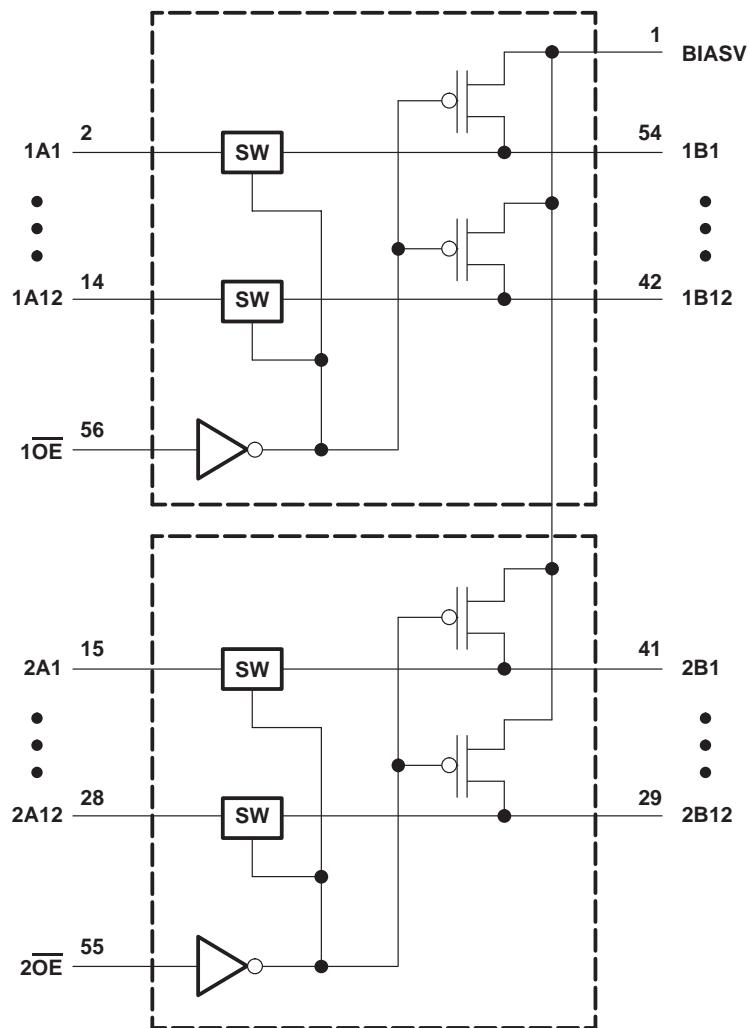
TA	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP – DL	Tube	SN74CBT16811CDL	CBT16811C
		Tape and reel	SN74CBT16811CDLR	
	TSSOP – DGG	Tube	SN74CBT16811CDGG	CBT16811C
		Tape and reel	SN74CBT16811CDGGR	
	TVSOP – DGV	Tape and reel	SN74CBT16811CDGVR	CY811C

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

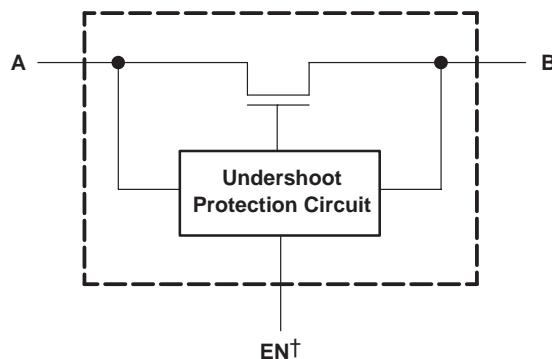
#### FUNCTION TABLE (each 12-bit bus switch)

INPUT $\overline{OE}$	INPUT/OUTPUT A	FUNCTION
L	B	A port = B port
H	Z	Disconnect B port = BIASV

logic diagram (positive logic)



simplified schematic, each FET switch (SW)



† EN is the internal enable signal applied to the switch.

# SN74CBT16811C

# 24-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS

**5-V BUS SWITCH WITH -2-V UNDERRIDE**  
SOD2402G - JANUARY 2000 - REVISED OCTOBER 2000

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to ground unless otherwise specified.

1. All voltages are with respect to ground unless otherwise specified.
2. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
3.  $V_I$  and  $V_O$  are used to denote specific conditions for  $V_{I/O}$ .
4.  $I_I$  and  $I_O$  are used to denote specific conditions for  $I_{I/O}$ .
5. The package thermal impedance is calculated in accordance with JESD 51-7.

### **recommended operating conditions (see Note 6)**

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	4	5.5	V
BIASV	Bias supply voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level control input voltage	2	5.5	V
V <sub>IL</sub>	Low-level control input voltage	0	0.8	V
V <sub>I/O</sub>	Data input/output voltage	0	5.5	V
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

NOTE 6: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004. BIASV is a supply voltage, not a control input.

SN74CBT16811C  
**24-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS  
5-V BUS SWITCH WITH -2-V UNDERSHOOT PROTECTION**

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
$V_{IK}$	Control inputs	$V_{CC} = 4.5$ V, $I_{IN} = -18$ mA					-1.8	V
$V_{IKU}$	Data inputs	$V_{CC} = 5$ V, $0$ mA $> I_I \geq -50$ mA, $V_{IN} = V_{CC}$ or GND, Switch OFF					-2	V
$V_{O(USP)}^{\ddagger}$		$V_{CC} = BIASV = 5$ V, $I_I = -10$ mA, $V_{IN} = V_{CC}$ or GND, Switch OFF			3			V
$V_O$	B port	$V_{CC} = 0$ V, BIASV = $V_X$ , $I_O = 0$			$V_X - 0.1$		$V_X$	V
$I_{IN}$	Control inputs	$V_{CC} = 5.5$ V, $V_{IN} = V_{CC}$ or GND					$\pm 1$	$\mu A$
$I_O$	B port	$V_{CC} = 4.5$ V, BIASV = 2.4 V, $V_O = 0$ , $V_{IN} = V_{CC}$ or GND			0.25			$mA$
$I_{OZ}^{\$}$		$V_{CC} = 5.5$ V, $V_O = 0$ to 5.5 V, $V_I = 0$ , $V_{IN} = V_{CC}$ or GND					$\pm 10$	$\mu A$
$I_{off}$		$V_{CC} = 0$ , $V_O = 0$ to 5.5 V, $V_I = 0$			10			$\mu A$
$I_{CC}$		$V_{CC} = 5.5$ V, $I_{I/O} = 0$ , $V_{IN} = V_{CC}$ or GND, Switch ON or OFF			3			$\mu A$
$\Delta I_{CC}^{\parallel}$	Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at $V_{CC}$ or GND			2.5			$mA$
$C_{in}$	Control inputs	$V_{IN} = 3$ V or 0			4.5			pF
$C_{io(OFF)}$	A port	$V_{I/O} = 3$ V or 0, Switch OFF, $V_{IN} = V_{CC}$ or GND			5.5			pF
$C_{io(ON)}$		$V_{I/O} = 3$ V or 0, Switch ON, $V_{IN} = V_{CC}$ or GND			15.5			pF
$r_{on}^{\#}$		$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V		$V_I = 2.4$ V, $I_O = -15$ mA	8	12		$\Omega$
		$V_{CC} = 4.5$ V	$V_I = 0$	$I_O = 64$ mA	3	6		
				$I_O = 30$ mA	3	6		
				$V_I = 2.4$ V, $I_O = -15$ mA	5	10		

$V_{IN}$  and  $I_{IN}$  refer to control inputs.  $V_I$ ,  $V_O$ ,  $I_I$ , and  $I_O$  refer to data pins.

† All typical values are at  $V_{CC} = 5$  V (unless otherwise noted),  $T_A = 25^\circ C$ .

‡  $V_{O(USP)}$  = A-port undershoot static protection.

§ For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current.

¶ This is the increase in supply current for each input that is at the specified voltage level, rather than  $V_{CC}$  or GND.

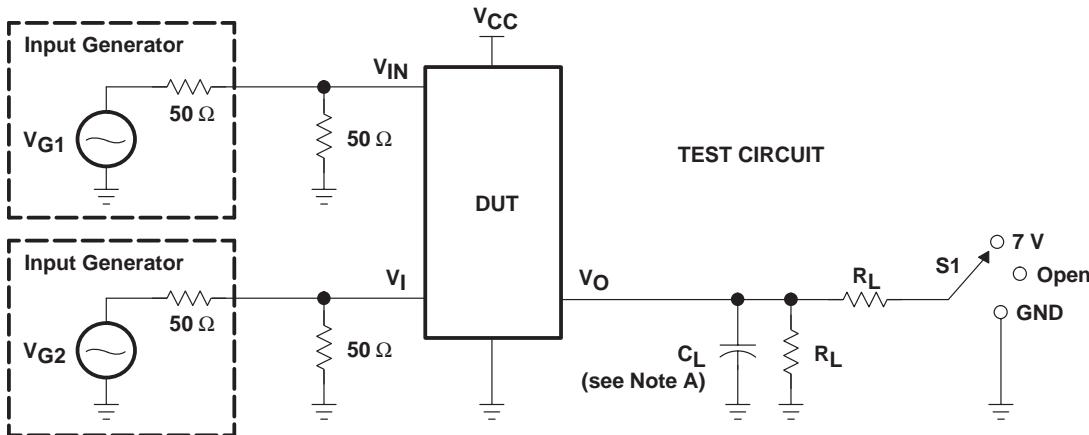
# Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

**switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)**

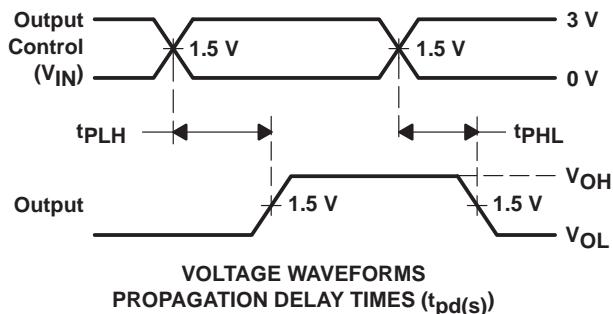
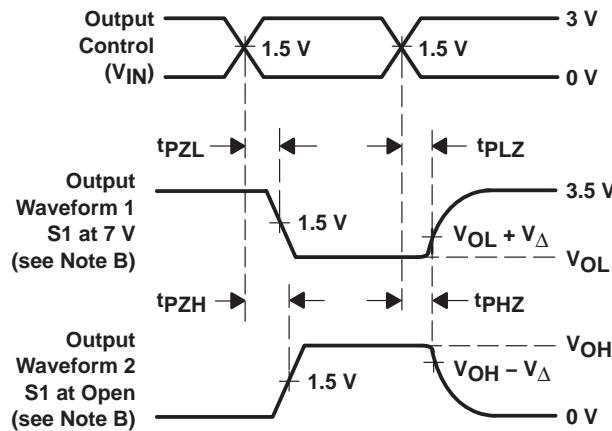
PARAMETER	TEST CONDITIONS	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V $\pm 0.5$ V		UNIT
				MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$		A or B	B or A	0.24		0.15		ns
$t_{PZH}$	BIASV = GND	$\overline{OE}$	A or B	6.5	1.5	6		ns
$t_{PZL}$	BIASV = 3 V			6.5	1.5	6		
$t_{PHZ}$	BIASV = GND	$\overline{OE}$	A or B	6.5	1.5	6		ns
$t_{PLZ}$	BIASV = 3 V			6.5	1.5	6		

|| The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

## PARAMETER MEASUREMENT INFORMATION



TEST	V <sub>CC</sub>	S1	R <sub>L</sub>	V <sub>I</sub>	C <sub>L</sub>	V <sub>Δ</sub>
t <sub>pd(s)</sub>	5 V ± 0.5 V 4 V	Open Open	500 Ω 500 Ω	V <sub>CC</sub> or GND V <sub>CC</sub> or GND	50 pF 50 pF	
t <sub>PLZ/tPZL</sub>	5 V ± 0.5 V 4 V	7 V 7 V	500 Ω 500 Ω	GND GND	50 pF 50 pF	0.3 V 0.3 V
t <sub>PHZ/tPZH</sub>	5 V ± 0.5 V 4 V	Open Open	500 Ω 500 Ω	V <sub>CC</sub> V <sub>CC</sub>	50 pF 50 pF	0.3 V 0.3 V

VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES (tpd(s))VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

NOTES:

- C<sub>L</sub> includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> ≤ 2.5 ns, t<sub>f</sub> ≤ 2.5 ns.
- The outputs are measured one at a time with one transition per measurement.
- t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
- t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd(s)</sub>. The tpd propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
- All parameters and waveforms are not applicable to all devices.

Figure 1. Test Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74CBT16811CDGGRE4	ACTIVE	TSSOP	DGG	56		TBD	Call TI	Call TI	-40 to 85		<span style="background-color: red; color: white; padding: 2px;">Samples</span>
74CBT16811CDGGRG4	ACTIVE	TSSOP	DGG	56		TBD	Call TI	Call TI	-40 to 85		<span style="background-color: red; color: white; padding: 2px;">Samples</span>
74CBT16811CDGVRE4	ACTIVE	TVSOP	DGV	56		TBD	Call TI	Call TI	-40 to 85		<span style="background-color: red; color: white; padding: 2px;">Samples</span>
74CBT16811CDGVRG4	ACTIVE	TVSOP	DGV	56		TBD	Call TI	Call TI	-40 to 85		<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CBT16811CDGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16811C	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CBT16811CDGVR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY811C	<span style="background-color: red; color: white; padding: 2px;">Samples</span>
SN74CBT16811CDL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16811C	<span style="background-color: red; color: white; padding: 2px;">Samples</span>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

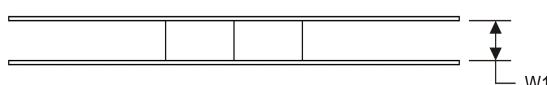
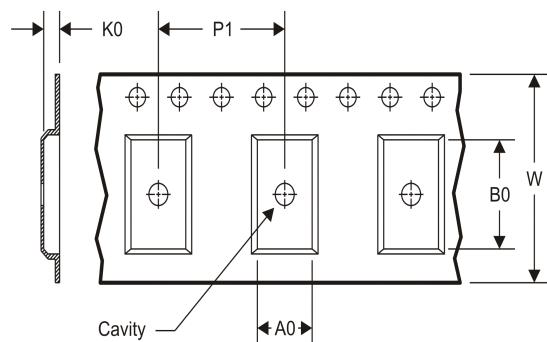
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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16811CDGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74CBT16811CDGVR	TVSOP	DGV	56	2000	330.0	24.4	6.8	11.7	1.6	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT16811CDGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0
SN74CBT16811CDGVR	TVSOP	DGV	56	2000	367.0	367.0	45.0

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

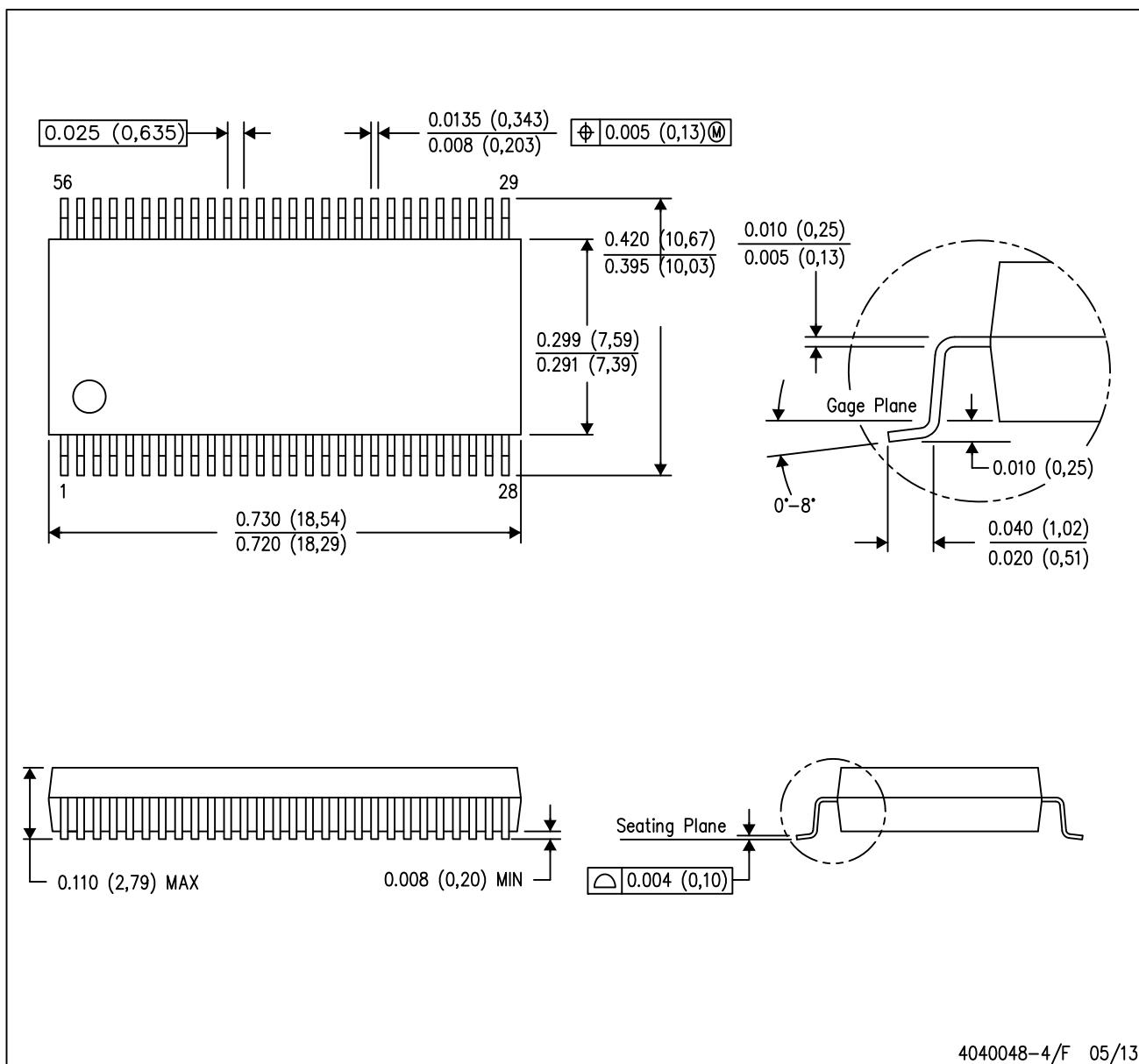
24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

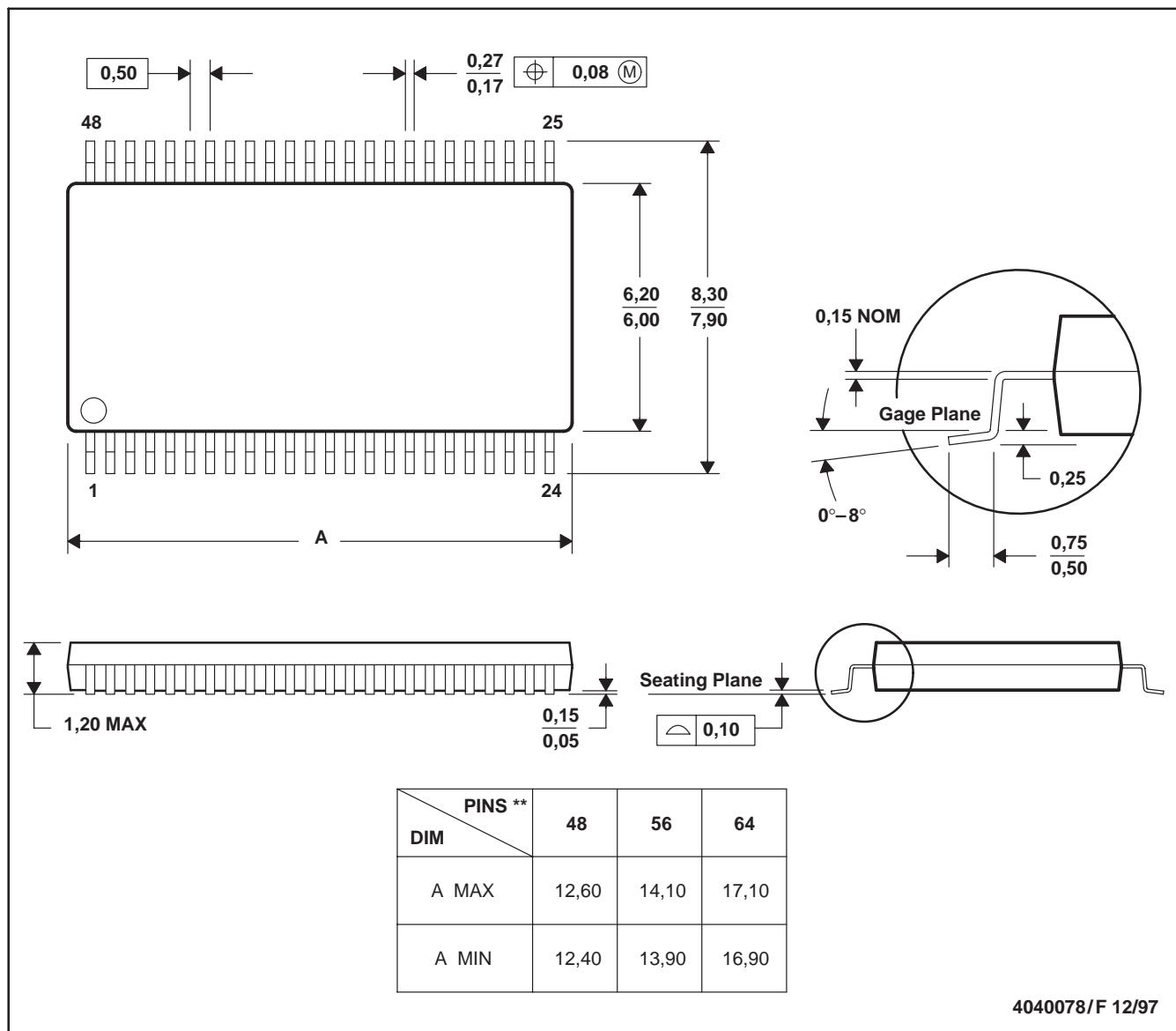
- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products	Applications
Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>
	<b>TI E2E Community</b>
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